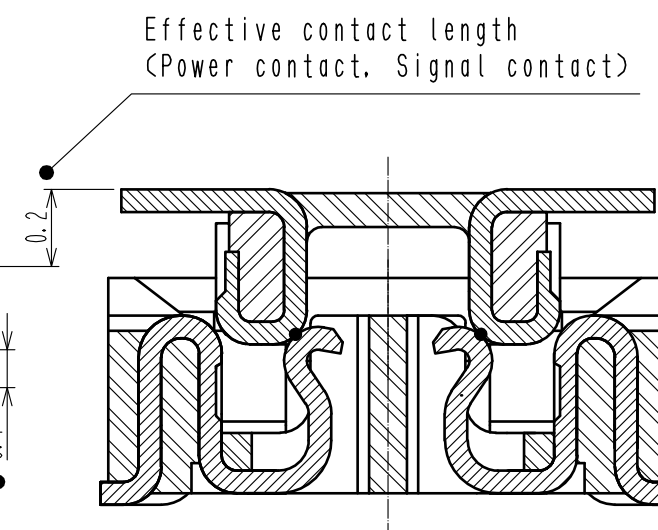
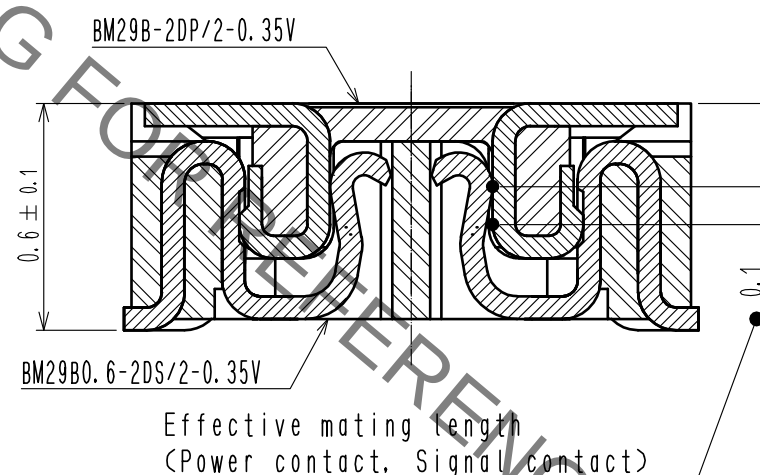
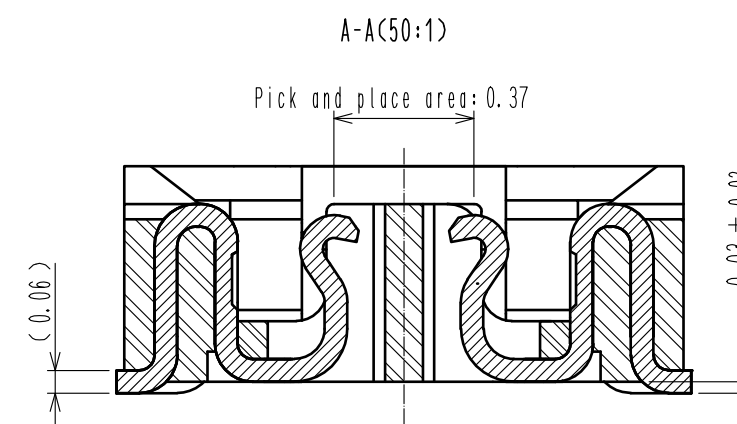
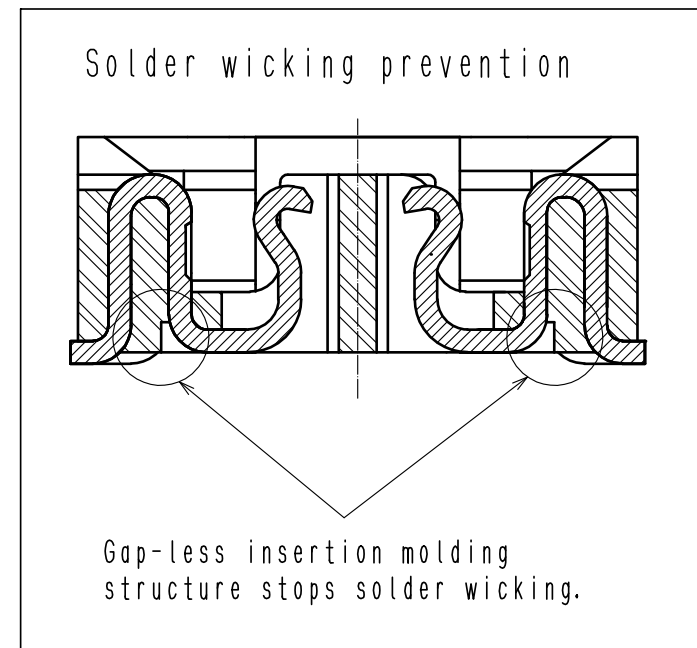
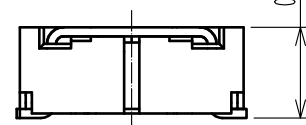
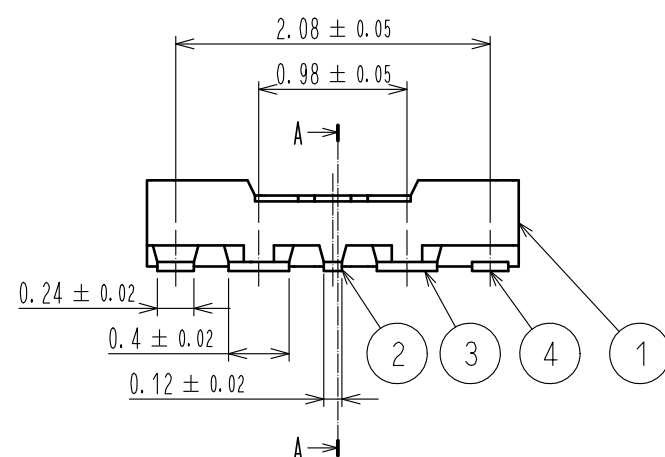
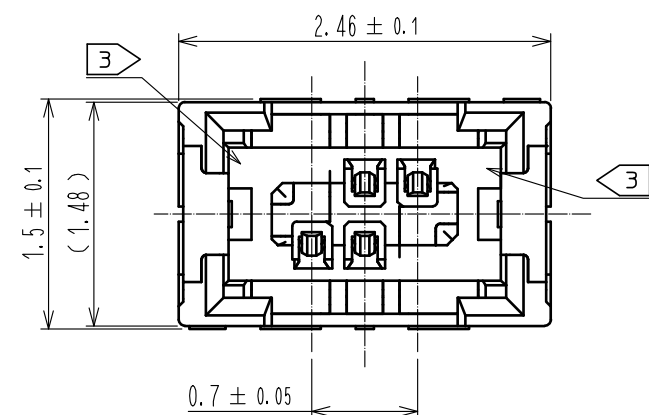


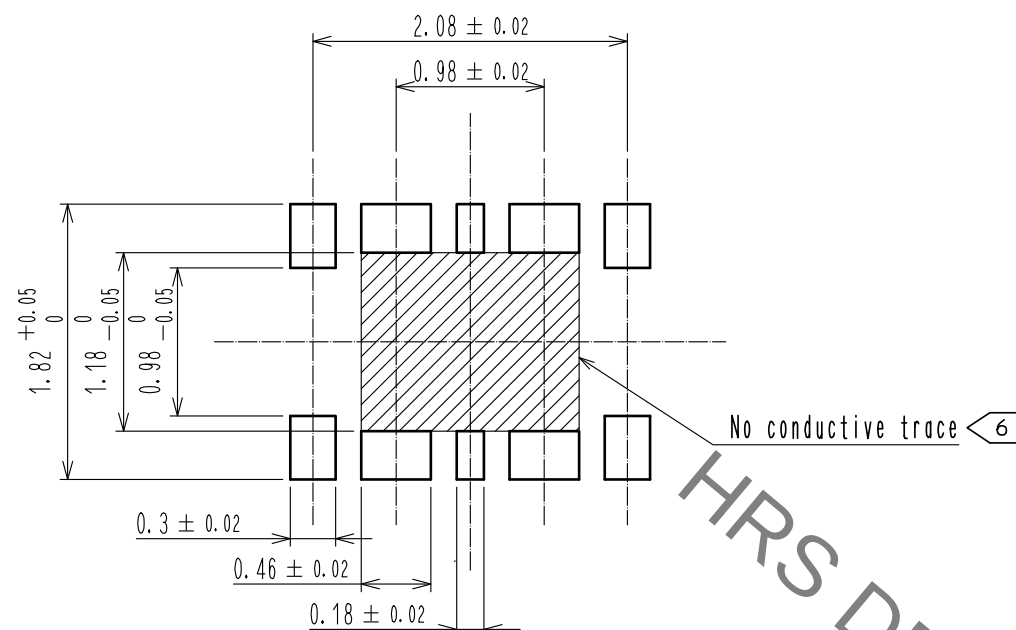
Jun.1.2020 Copyright 2020 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.



- NOTE 1 . All lead co-planarity shall be 0.08mm MAX.
2 . Contact plating specifications
Contact area : Gold 0.05 μ m MIN
SMT lead : Gold 0.05 μ m MIN
Under plating : Nickel 1 μ m MIN
(Surface : Sealing)
3 . HRS mark and CAV No. are indicated in approx. position shown.

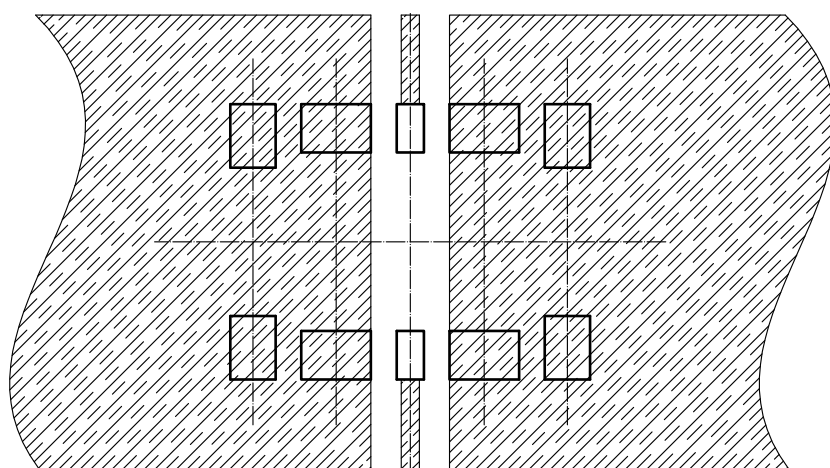
4	PHOSPHOR BRONZE	2	8	PS	CLEAR, REINFORCEMENT COLLAR
3	PHOSPHOR BRONZE	2	7	PS	BLACK, PLASTIC REEL
2	PHOSPHOR BRONZE	2	6	POLYESTER	CLEAR, COVER TAPE
1	LCP	UL94 V-0, BLACK	5	PS	SMOKE GRAY, EMBOSSED CARRIER TAPE
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 20 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED
	HIROSE ELECTRIC CO., LTD.	APPROVED : MO. ISHIDA	16.01.06	DRAWING NO.	EDC-362699-53-01
		CHECKED : WR. FUKUCHI	16.01.06	PART NO.	BM29B0.6-2DS/2-0.35V<53>
		DESIGNED : TY. YAMASAKI	16.01.06	CODE NO.	CL673-7001-0-53
		DRAWN : KR. AJITO	16.01.06		

◆Recommended PCB layout

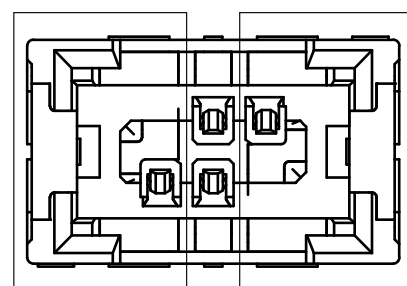


◆Recommended metal mask dimensions
Metal mask thickness : 100 μm
(Open ratio : 100% for PCB layout)

◆Recommended electrical circuit layout

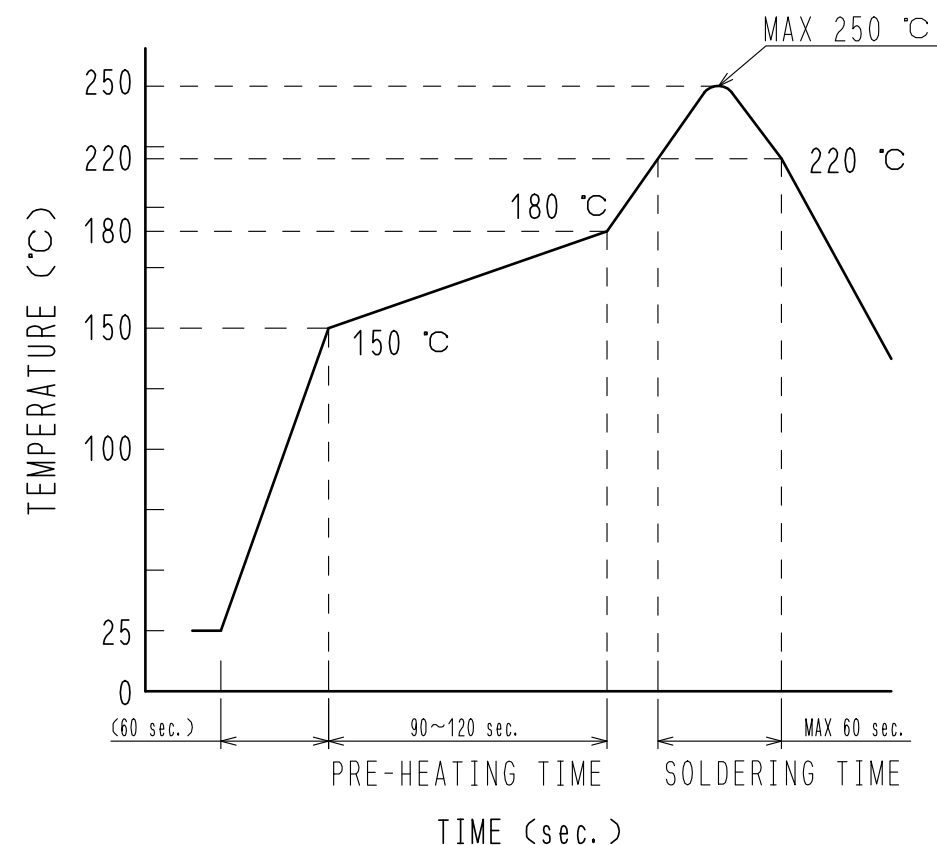


Electrical circuit



Power pin unit

4 Recommended reflow temperature profile using lead-free solder paste.



Reflow method: IR reflow
Number of reflow cycles: 2 cycles MAX.
1) Reflow time
Duration above 220°C: 60 sec MAX.
(Peak temperature: 250°C MAX)
2) Pre-heat time
Pre-heat temperature (MIN): 150°C
Pre-heat temperature (MAX): 180°C
Pre-heat time: 90~120 sec.

- 4 The temperatures mentioned above refer to the PCB surface temperature near the connector leads. The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.
- 5 Please contact us in case you will make different settings from our recommendation.
- 6 For the routing on the indicated PCB surface, apply solder resist in order for the insulation treatment.

HRS

DRAWING NO.	EDC-362699-53-01
PART NO.	BM29B0. 6-2DS/2-0.35V(53)
CODE NO.	CL673-7001-0-53

2/3

Jun.1.2020 Copyright 2020 HIROSE ELECTRIC CO., LTD. All Rights Reserved.
In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

